

ABSTRACT

SEMICONDUCTOR SYSTEM WITH FINE PITCH LEAD FINGERS AND METHOD OF MANUFACTURE THEREOF

A method for manufacturing a semiconductor package system includes: providing a die having a plurality of contact pads; forming a leadframe having a plurality of lead fingers with flat tops of predetermined lengths, the plurality of lead fingers having a fine pitch and each having a trapezoidal cross-section; attaching a plurality of bumps to the plurality of lead fingers, the plurality of bumps on the tops, extending beyond the widths of the trapezoidal cross-sections, and clamping down on the two sides of each of the plurality of lead fingers; attaching a plurality of bond wires to the plurality of contact pads; attaching the plurality of bond wires to the plurality of bumps; and forming an encapsulant over the plurality of lead fingers, the die, and the plurality of bond wires, the encapsulant leaving lower surfaces of the plurality of lead fingers exposed.

(FIG. 1)